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Comments from the Editors

Dear ACM/SIGDA members,

The SIGDA election result is out. Congratulations to the new SIGDA EC members! Meanwhile, we want to express our sincere appreciation to the past chair of SIGDA, Dr. Sharon Hu, and all the past EC members for their great contributions to the SIGDA community.

We are also excited to present to you July E-Newsletter. We encourage you to invite your students and colleagues to be a part of the SIGDA newsletter. The newsletter covers a wide range of information from the upcoming conferences and hot research topics to technical news and activities from our community. Get involved and contact us if you want to contribute an article or announcement.

The newsletter is evolving. Please let us know what you think.

Happy reading!

[Debjit Sinha](#), Keni Qiu, Editors-in-Chief, SIGDA E-News

To renew your ACM SIGDA membership, please visit <http://www.acm.org/renew> or call between the hours of 8:30am to 4:30pm EST at +1-212-626-0500 (Global), or 1-800-342-6626 (US and Canada). For any questions, contact acmhelp@acm.org.

SIGDA E-News Editorial Board:

[Debjit Sinha](#), E-Newsletter co Editor-in-Chief

Keni Qiu, E-Newsletter co Editor-in-Chief

Xiang Chen, E-Newsletter Associate Editor for SIGDA News column

Yanzhi Wang, E-Newsletter Associate Editor for SIGDA Local chapter news column

Pingqiang Zhou, E-Newsletter Associate Editor for SIGDA Awards column

Xun Jiao, E-Newsletter Associate Editor for SIGDA What is column

Jayita Das, E-Newsletter Associate Editor for SIGDA Funding opportunities column

Rajsaktish Sankaranarayanan, E-Newsletter Associate Editor for SIGDA Researcher spotlight column

Xin Zhao, E-Newsletter Associate Editor for SIGDA Paper submission deadline column

Ying Wang, E-Newsletter Associate Editor for SIGDA Technical activities column

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News on the SIGDA EC Board

Dear SIGDA members,

I am pleased to inform you that the SIGDA election result is out. The following volunteers will form the new SIGDA EC board:

Chair:

Yiran Chen, Duke University, USA

Executive Committee:

[Aida Todri-Sanial](#), CNRS, University of Montpellier, France

[Sudeep Pasricha](#), Colorado State University, USA

Yuan-Hao Chang, Academia Sinica, Taiwan

Wanli Chang, University of York, UK

Jingtong Hu, University of Pittsburgh, USA

Yu Wang, Tsinghua University, P.R. China

Congratulations to the elected SIGDA EC members! The new leadership team will take over July 1.

I also want to express my sincere gratitude to the not elected candidates for their willingness to be nominated in this election cycle.

Active and devoted volunteers are the key to the success of SIGDA. Please always feel free to reach out if you want to volunteer in any specific capacity. To volunteer, check out

<https://www.acm.org/about-acm/get-involved> or contact any of the SIGDA EC members.

SIGDA has a current call for nomination for the Diversity and Ethics Chair position. Please consider nominating qualified volunteers as candidates for this position. Self-nominations are also welcome.

Submit your nomination at

https://docs.google.com/forms/d/e/1FAIpQLSfNI4Rzg8YmnjuVAm67jyfUdJlQvnl7Hy2_opSu...

-Sharon Hu (past chair of SIGDA)

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SIGDA News

(1) "U.S. Blocks Chinese Deal for Magnachip"

[\[https://www.eetimes.com/u-s-blocks-chinese-deal-for-magnachip/\]](https://www.eetimes.com/u-s-blocks-chinese-deal-for-magnachip/)

A U.S. interagency panel has moved to block the acquisition of a South Korean chipmaker by a Chinese investor, signaling what observers say is a significant expansion of U.S. jurisdiction in curtailing Chinese access to strategic semiconductor technologies.

(2) "U.S. Takes First Steps Toward Resilient Supply Chains"

[\[https://www.eetimes.com/u-s-takes-first-steps-toward-resilient-supply-chains/\]](https://www.eetimes.com/u-s-takes-first-steps-toward-resilient-supply-chains/)

The marathon race that is the rebuilding of American technology supply chains has commenced, with cautious optimism that initial efforts will eventually yield resilient U.S. manufacturing and distribution frameworks for semiconductors and key energy technologies.

(3) "GlobalFoundries Expands Manufacturing to Singapore"

[\[https://www.eetimes.com/qualcomm-mediatek-fill-vacuum-hisilicon-left-in-smartpho...\]](https://www.eetimes.com/qualcomm-mediatek-fill-vacuum-hisilicon-left-in-smartpho...)

Qualcomm and MediaTek have plugged the gap that Huawei left when the US government effectively forced Huawei subsidiary HiSilicon out of the smartphone chip business last year as part of the trade war between China and the US.

(4) "Qualcomm, MediaTek Fill Vacuum HiSilicon Left in Smartphones"

[\[https://www.eetimes.com/multi-node-quantum-network-on-the-horizon/\]](https://www.eetimes.com/multi-node-quantum-network-on-the-horizon/)

Researchers at the Dutch QuTech research center in Delft have demonstrated a multi-node quantum network capable of connecting three quantum processors, or 'qubits' .

(5) "Diamond Quantum Technology for Medical Imaging"

[\[https://www.eetimes.com/diamond-quantum-technology-for-medical-imaging/\]](https://www.eetimes.com/diamond-quantum-technology-for-medical-imaging/)

The performance of quantum states offers excellent potential for highly sensitive sensors to measure a range of variables such as magnetism, temperature, and electric fields.

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SIGDA Partner Journal

1) Message from the ACM TODAES (Transactions on Design Automation of Electronic Systems) Editor in Chief, X. Sharon Hu:

It has been a year since I became the EiC of TODAES. I would like to share some exciting news about TODAES with the EDA community.

As a premier journal in the EDA area, TODAES has continued to strive for shorter submission-to-first-review and accept-to-publication time. This past year TODAES has reduced the average time from submission to first review to 45 days (compared to 81 days in the previous year)! (This is an effort of all the Associated Editors and Reviewers, many are readers of this newsletter. Kudos to them!) Once a paper is accepted, TODAES aims to publish the paper formally within 6 months. I am proud to say that we have achieved this goal in the past year! TODAES continues to see a steady increase of quality submissions. From June 1st, 2019 to May 31, 2019, the total number of submissions has increased by close to 20% of that in the previous cycle and by 34% of the number two years ago!

TODAES Best Paper award is prestigious and extremely competitive. It is selected based on the evaluation of the TODAES editorial board members and a two-round selection process by the Best Paper Selection Committee consisting of EDA experts. The 2021 award goes to Sumit K. Mandal, Ganapati Bhat, Janardhan Rao Doppa, Partha Pratim Pande, Umit Y. Ogras, for their paper titled An Energy-Aware Online Learning Framework for Resource Management in Heterogeneous Platforms, and published in May 2020. Congratulations to all the authors!

We have two open Call for Papers for special issues:

* High-Level Synthesis for FPGA: Next-Generation Technologies and Applications (deadline July 10th) - https://dl.acm.org/pb-assets/static_journal_pages/todaes/pdf/CfP-SI-TODAES-HLS_v...

* Special Issue on Energy-Efficient AI Chips and Applications for Edge and Server Systems (deadline July 15th).

TODAES is always in need for qualified reviewers. If you are interested in becoming a reviewer for TODAES, please fill the form at this link

https://docs.google.com/forms/d/e/1FAIpQLScSOiAK5KEGP9bMLw5Rrmph9SPOYdkLtIA_ECO7...

Thank you for following this column in the SIGDA Newsletter and your continued support to ACM TODAES. To learn more about TODAES, check out <https://dl.acm.org/journal/todaes>.

2) HACK@DAC - From TODAES Associate Editor Ahmad Reza Sadeghi <ahmad.sadeghi@trust.tu-darmstadt.de>

HACK@DAC '21 is the DAC sequel of the world' s largest hardware security competition HACK@Event franchise, a premier hardware security competition and a venue for scientists and industry experts to discover, exploit and mitigate security-critical vulnerabilities and design flaws in system-on-a-chip (SoC). HACK@DAC '21 mimics real-world scenarios where security engineers have to find and exploit security-critical vulnerabilities in hardware. The vulnerabilities are diverse and range from data corruption to leaking sensitive information leading to compromise of the entire computing platform. The open-source SoC riddled with security vulnerabilities has been co-developed by Intel, the Technical University of Darmstadt, and Texas A&M University. The participants are encouraged to use any tools and techniques with a focus on theory, tooling, and automation.

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Call for Participation

ISLPED '21 is waiting for you!

The upcoming International Symposium on Low Power Electronics and Design (ISLPED) is the premier forum for presentation of innovative research in all aspects of low power electronics and design, ranging from process technologies and analog/digital circuits, simulation and synthesis tools, system-level design and optimization, to system software and applications.

It will take place on July 26 – 28 as a virtual event.

Check out the program here:

https://www.islped.org/2021/preliminary_program.php#PreliminaryProgram

Registrations are open, all information is available on the website.

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Paper Submission Deadlines

FPT'21 - Int'l Conference on Field-Programmable Technology
Auckland, New Zealand
Deadline: Jul 19, 2021 (Abstracts due: Jul 12, 2021)
Dec 6-10, 2021
<http://icfpt.org>

DAForum'21 - SIGDA/IEEE CEDA Ph.D. Forum at DAC 2021
San Francisco, CA
Deadline: July 20, 2021
Dec 6, 2021
<https://easychair.org/cfp/daforum21>

IWBDA'21 - Int'l Workshop on Bio-Design Automation
Online
Deadline: Jul 30, 2021 (Abstracts due: Jul 30, 2021)
Sept 20-24, 2021
<http://www.iwbdaconf.org/2021>

ISPD'22 - ACM International Symposium on Physical Design
Deadline: October 8, 2021 (Abstracts due: October 1, 2021)
Banff, Alberta, Canada, with virtual participation across the world
March 27-30, 2022
<http://www.ispd.cc>

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Upcoming Conferences and Symposia

ICDCS'21 – IEEE Int'l Conference on Distributed Computing Systems
Virtual
Jul 7 - 10, 2021
<https://icdcs2021.us/>

ISVLSI' 21 – IEEE Computer Society Annual Symposium on VLSI
Tampa, Florida
Jul 7-9, 2021
<http://www.ieee-isvlsi.org>

ISED' 21 – 10th Int' l Symposium on Embedded Computing & System Design
Kollam, India
Jul 16-18, 2021
<http://isedconf.org>

IWLS'21 - International Workshop on Logic & Synthesis
Virtual conference
Jul 19-21, 2021
<https://www.iwls.org>

ISLPED' 21 – ACM/IEEE Int' l Symposium on Low Power Electronics and Design
Hybrid Zoom/Boston, MA
Jul 26-28, 2021
<http://www.islped.org>

ASYNC'21 – IEEE Int' l Symposium on Asynchronous Circuits and Systems

Virtual Conference

Sept 7-10, 2021

<http://asynsymposium.org>

PACT'21 - Int'l Conference on Parallel Architectures and Compilation Techniques

Virtual Conference

Sept 26-28, 2021

<http://www.pactconf.org>

VLSI-SoC' 21 – IFIP/IEEE Int' l Conference on Very Large Scale Integration

Virtual conference

Oct 4-8, 2021

<http://www.vlsi-soc.com>

BioCAS'21 – Biomedical Circuits and Systems Conference

Berlin, Germany

Oct 7-9, 2021

<https://2021.ieee-biocas.org/>

ESWEEK'21 - Embedded Systems Week (CASES, CODES+ISSS, and EMSOFT)

Virtual Conference

Oct 10-15, 2021

<http://www.esweek.org>

NOCS'21 – IEEE/ACM Int' l Symposium on Networks-on-Chip (co-located with ESWEEK 2021)

Virtual Conference

Oct 14-15, 2021

<https://nocs2021.github.io>

MICRO' 21 – IEEE/ACM Int'l Symposium on Microarchitecture

Athens, Greece

Oct 16-20, 2021

<http://www.microarch.org/micro54>

ICCD' 21 – IEEE Int' l Conference on Computer Design

Virtual Conference

Oct 24-27, 2021

<http://www.iccd-conf.com>

BodyNets'21 – Int' l Conference on Body Area Networks

Virtual Conference

Oct 25-26, 2021

<http://www.bodynets.org>

ICCAD' 21 – IEEE/ACM Int' l Conference on Computer-Aided Design

Virtual Conference

Nov 1-4, 2021

<http://www.iccad.com>

DAC' 21 – Design Automation Conference

San Francisco

Dec 5–9, 2021

<http://www.dac.com/>

HOST'21 – IEEE Int' l Symposium on Hardware-Oriented Security and Trust

Washington DC

Dec 12-15, 2021

<http://www.hostsymposium.org>

HiPC'21 – IEEE Int'l Conference on High Performance Computing, Data, And Analytics

Bangalore, India

Dec 17-20, 2021

<http://www.hipc.org>

iSES' 21 – IEEE Int' l Symposium on Smart Electronic Systems

Jaipur, India

Dec 20-22, 2021

<http://www.ieee-ises.org>

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SIGDA Awards

1. SIGDA Student Research Competition (SRC) Gold Medalists won ACM SRC Grand Finals

Graduate: First Place

Jiaqi Gu, University of Texas at Austin

Research Advisors: David Z. Pan and Ray T. Chen

“Light in Artificial Intelligence: Efficient Neuromorphic Computing with Optical Neural Networks” (ICCAD 2020)

Deep neural networks have received an explosion of interest for their superior performance in various intelligent tasks and high impacts on our lives. The computing capacity is in an arms race with the rapidly escalating model size and data amount for intelligent information processing. Practical application scenarios, e.g., autonomous vehicles, data centers, and edge devices, have strict energy efficiency, latency, and bandwidth constraints, raising a surging need to develop more efficient computing solutions. However, as Moore's law is winding down, it becomes increasingly challenging for conventional electrical processors to support such massively parallel and energy-hungry artificial intelligence (AI) workloads...

Undergraduate: Second Place

Chuangtao Chen, Zhejiang University

Research Advisor: Cheng Zhuo

“Optimally Approximated Floating-Point Multiplier” (ICCAD 2020)

At the edge, IoT devices are designed to consume the minimum resource to achieve the desired accuracy. However, the conventional processors, such as CPU or GPU, can only conduct all the computations with predetermined but sometimes unnecessary precisions, inevitably degrading their energy efficiency. When running data-intensive applications, due to the large range of input operands, most conventional processors heavily rely on floating-point units (FPUs). Recently, approximate computing has become a promising alternative to improve energy efficiency for IoT devices on the edge, especially when running inaccuracy-tolerable applications. For various data-intensive tasks on edge devices, multiplication is a common but the most energy consuming one among different floating-point operations. As a common arithmetic component that has been studied for decades [1]–[3], the past focus on the FP multiplier is accuracy and performance...

For more details, please refer to <https://www.sigda.org/sigda-events/src/>.

2. Call for Nominations: SIGDA Pioneering Achievement Award

Deadline: Aug. 31, 2021

Presented by the ACM Special Interest Group on Design Automation.

Description: To honor a person for lifetime, outstanding contributions within the scope of electronic design automation, as evidenced by ideas pioneered in publications, industrial products, or other relevant contributions. The award is based on the impact of the contributions throughout the nominee's lifetime.

Background: The ACM Special Interest Group on Design Automation sponsors or co-sponsors the ACM Transactions on Design Automation of Electronic Systems Best Paper Award, the William McCalla Award for best paper at the International Conference on Computer-Aided Design, and the ACM/IEEE A. Richard Newton Technical Impact in Electronic Design Automation Award which is given to authors of a publication authored at least ten years earlier and that has had an outstanding contribution to the field of EDA. In addition, SIGDA sponsors the ACM Outstanding Ph.D. Dissertation Award in Electronic Design Automation which is given each year to a graduating Ph.D. student in recognition of his/her thesis contributions to advancement in the EDA field. The Pioneering Achievement Award complements these awards and is intended for contributors whose impact is typically recognized over a lifetime of outstanding achievements.

Eligibility: Open to researchers in the field of electronic design automation who have had outstanding contributions in the field during their lifetime. Current members of the Board of the ACM Special Interest Group on Design Automation, or members of the Award Selection Committee are ineligible for the award. The awardee is invited to give a lecture at a SIGDA-sponsored event.

Award Items: A plaque for the awardee, a citation, and \$1000 honorarium. The honorarium will be funded by the SIGDA annual budget.

Nominee Solicitation: The call for nominees will be published by email to members of SIGDA, on the web site of ACM's Special Interest Group on Design Automation, and in the SIGDA newsletter. The nomination should be proposed by someone other than the nominee. The nomination materials should be emailed to SIGDA-Award@acm.org (Subject: ACM/SIGDA Pioneering Achievement Award). Nominations for the award should include:

A nomination letter that gives: a 100-word description of the nominee's contribution and its impact; a 750-word detailed description of up to 10 of the nominee's major products (papers, patents, software, etc.), the contributions embodied in those products, and their impact; a list of at most 10 citations to the major products discussed in the description.

Three letters of recommendation (not including the nominator or nominee).

Contact information of the nominator.

In addition to the evidence of impact, the nomination form will include biographical information (including education and employment), professional activities, publications, and recognition. Three endorsements attesting to the impact of the work may be included.

Award Committee: Selection will be made by the ACM Special Interest Group in Design Automation Executive Committee based on the recommendation of a Pioneer Award committee. The Committee will meet to review nominations, review the recommendations of the Pioneer Award Committee, and make a selection. After selection, the committee will contact the recipient to ensure that the award will be accepted and he or she will be able to deliver the talk at the SIGDA Annual Member Meeting and Dinner at ICCAD.

All standard conflict of interest regulations as stated in ACM policy will be applied (see <https://awards.acm.org/conflict-of-interest>). Any awards committee members will recuse themselves from consideration of any candidates where a conflict of interest may exist.

Schedule: The call for nominees will be published annually. The nomination deadline is Aug 31st. The award will be announced at one or more subsequent SIGDA events and the awardee will be invited to give a talk on his/her work at the SIGDA Annual Member Meeting and Dinner at ICCAD.

Selection/Basis for Judging: This award honors an individual who has made an outstanding technical contribution in the scope of electronic design automation throughout his or her lifetime. The award is based on the impact of the contributions as indicated above. Nominees from universities, industry, and government worldwide will be considered and encouraged. The award is not a best paper or initial original contribution award. Instead, it is intended for lifetime, outstanding contributions within the scope of electronic design automation, throughout the nominee's lifetime.

Presentation: The award will be presented annually at the SIGDA Annual Member Meeting and Dinner at ICCAD.

Publicity: In ACM/SIGDA publications and at conferences sponsored by ACM/SIGDA.

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Technical Activities

1. "MLPerf Deadlock: Google and Nvidia Tied for First Place"

The fourth round of the MLPerf AI training system benchmarks attracted 650 submissions – how has performance increased since last year?

<https://www.eetasia.com/mlperf-deadlock-google-and-nvidia-tied-for-first-place/>

2. "New Intel XPU Innovations Target HPC and AI"

Sapphire Rapids with built-in HBM raises performance bar; Intel's GPU, networking and storage capabilities enhance HPC toolbox...

<https://www.edacafe.com/nbc/articles/1/1847935/New-Intel-XPU-Innovations-Target-...>

3. "Depth Sensing Takes Machine Vision into Another Dimension"

What can human vision do that computer vision can't?

<https://www.eetimes.eu/depth-sensing-takes-machine-vision-into-another-dimension...>

4. "Siemens, AMD, and Microsoft collaborate on EDA in the cloud"

The recently announced partnership between Siemens EDA, AMD, and Azure was purpose-built to highlight the reduction in time and costs of cloud usage which is achievable vis-à-vis the implementation of best practices and usage guidelines for EDA cloud computing...

<https://iot.eetimes.com/siemens-amd-and-microsoft-collaborate-on-eda-in-the-clou...>

Job Openings:

1. University of Southern California United States

Job Title: Professor and Chair of Computer Science

Description: The USC Viterbi School of Engineering at the University of Southern California invites nominations and applications for Chair of the Department of Computer Science. We are seeking an individual who can provide strong, dynamic and innovative leadership for advancing excellence in research, teaching, and service to the professional community. The position is at the tenured Professor rank, starting either Fall 2021 or Spring 2022, and with an initial Chair term of 3 years. In addition to a proven record of scholarly achievement, the candidate must also possess visionary technical leadership, a firm commitment to computer science education, as well as strong management and interpersonal skills. The candidate should have an earned doctorate in computer science or in a closely allied field and be qualified for a tenured full professor appointment. To receive

full consideration, candidates should apply on-line at <https://usccareers.usc.edu/>. Applicants must submit a cover letter describing their leadership and administrative experiences, a statement describing their vision and goals as Chair, and a statement about their approach to diversity, equity and inclusion in higher education. A complete curriculum vitae, as well as research and teaching statements, must also be submitted. References will be requested at a later time. Applications received by August 31, 2021, will be given full consideration; those received after this deadline may also be considered.

2. Hong Kong University of Science and Technology (Guangzhou), China

Job Title: Founding Tenured/Tenure-Track Faculty in Microelectronics

Description: Microelectronics Thrust has multiple tenured/tenure-track positions at the ranks of Assistant Professor, Associate Professor, and Professor. Applicants should have a PhD degree and research in areas such as electronic design automation; photonic design automation; processor, memory, and storage system architecture; reconfigurable architecture; interconnection network; multiprocessor system; neural computing; approximate computing; quantum computing; hardware-software codesign; compilation techniques; operating system; system software; power management; thermal management; embedded system; system-on-chip; system-in-package; integrated photonic circuit; RF/mm-Wave/terahertz technology; modeling and simulation technology; emerging technology. English is the instruction and administration medium at the Guangzhou campus, and a good command of written and spoken English is required. Applicants of tenure-track Assistant Professor should demonstrate strong research and teaching potentials. Applicants of Associate Professor should have a proven record in research, teaching, student supervision, and funding. Applicants of Professor should have world-class academic achievements, international academic leadership, and an established track record in teaching, student supervision and funding. Applications should be submitted through the HKUST Recruitment System (<https://facrecruit.hkust.edu.hk>) which will be open until the positions are filled. If there is any question, please contact the Acting Head, Prof. Jiang Xu, at jiang.xu@ust.hk. HKUST is committed to equal opportunity and diversity in recruitment and employment. We strongly encourage candidates of diverse backgrounds to apply.

3. British Columbia Institute of Technology, Canada

Job Title: Associate Dean of School of Computing and Academic Studies

Description: The Associate Dean recognizes opportunities and changes in the IT, computing and related industry sectors. These will be addressed through planning and enabling appropriate change initiatives to ensure currency, program quality and viability of programs in areas of responsibility. The incumbent will provide leadership that connects the Computing area to the strategic initiatives of the Institute. DUTIES AND RESPONSIBILITIES: Establishing and fostering external relationships with industry, professional organizations, educational institutions and other bodies Managing departmental issues related to education such as enrollments and student success Building relationships with programs and support areas as appropriate to the areas of responsibility Administering the operating budget allocated to the areas of responsibility and securing revenue objectives through {part-time Studies and Industry Services Contributing as a member of the Institute's management team. At BCIT, we strive to recruit and select the right talent that best fits our organization's requirements. We encourage applicants to review BCIT's Leadership Competency Model prior to applying for this position to better understand the skills and behaviors that leaders at all levels at BCIT need to demonstrate in order to support our desired organizational culture and deliver our mandate and vision. In your application, please refer to <https://careers.bcit.ca/postings/3781>

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Notice to Authors

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This newsletter is a free service for current SIGDA members and is added automatically with a new SIGDA membership.

Circulation: 2,700

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